

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An optical interconnection circuit between chips, comprising:

a substrate;

a first ~~micro-tile~~ element having a light emitting function provided on the substrate by an adhesive;

a second ~~micro-tile~~ element having a light receiving function provided on the substrate by an adhesive;

an optical wave-guide optically connecting the first ~~micro-tile~~ element and the second ~~micro-tile~~ element with each other, and including an optical wave-guide member formed on the substrate,

wherein the optical wave-guide being is in contact with and covering at least a part of a light emitting part of ~~covers the first micro-tile element such that at least a light emitting part of the first micro-tile element is covered,~~

the optical wave-guide being in contact with and covering at least a part of a light receiving part of ~~and is in contact with and covers the second micro-tile element such that at least a light receiving part of the second micro-tile element is covered;~~ and

an electrode provided on the substrate and ~~electrically~~ connected to at least one of the first ~~micro-tile~~ element and the second ~~micro-tile~~ element.

2. (Original) The optical interconnection circuit between chips according to claim 1,

the electrode being a bonding pad which is a wiring electrode for an integrated circuit chip mounted onto the substrate.

3. (Original) The optical interconnection circuit between chips according to claim 1,

the electrode being a bonding pad in a case of an integrated circuit chip being flip-chip mounted onto the substrate.

4. (Original) The optical interconnection circuit between chips according to claim 2,

further including a bump composed of a convex conductive member and formed on the integrated circuit chip, the bump being electrically connected to at least one of an input terminal and an output terminal of the integrated circuit chip, and being bonded to the electrode.

5. (Currently Amended) The optical interconnection circuit between chips according to ~~claim 2~~ claim 1,

~~the integrated circuit chip including at least a plurality of integrated circuit chips being which are~~ mounted onto the substrate; and

a signal being transmitted among the plurality of integrated circuit chips via at least the first ~~micro-tile~~ element, the second ~~micro-tile~~ element, and the optical wave-guide.

6. (Currently Amended) The optical interconnection circuit between chips according to claim 1, further comprising additional

~~the second micro-tile element including at least a plurality of second micro-tile elements; and~~

~~the plurality of second micro-tile elements being optically connected to a single of the optical wave-guide.~~

7. (Currently Amended) The optical interconnection circuit between chips according to claim 1,

the first ~~micro-tile~~ element emitting light which is to be a clock signal.

8. (Currently Amended) ~~An~~ The optical interconnection circuit between chips,
~~comprising: according to claim 2,~~
~~_____ a substrate;~~
~~_____ a plurality of first elements having a light emitting function fixed on the~~
~~substrate by an adhesive;~~
~~_____ a plurality of second elements having a light receiving function fixed on the~~
~~substrate by an adhesive;~~
~~_____ a plurality of optical wave-guides that include an optical wave-guide member~~
~~formed on the substrate; and~~
~~_____ a plurality of integrated circuit chips that are mounted onto the substrate,~~
~~_____ the plurality of integrated circuit chips including an integrated circuit to time~~
~~control and an integrated circuit to provide driving,~~
~~_____ at least one of the plurality of optical wave-guides provided between the~~
~~integrated circuit to time control and the integrated circuit to provide driving, and~~
~~_____ the at least one of the plurality of optical wave-guides optically connecting at~~
~~least one of the plurality of first elements and at least one of the plurality of second elements~~
~~_____ the substrate being an element of a flat panel display;~~
~~_____ at least an integrated circuit to time control and an integrated circuit to provide~~
~~driving being mounted onto the substrate as the integrated circuit chip; and~~
~~_____ the optical wave guide including at least one optical wave guide which is~~
~~provided between the integrated circuit to time control and the integrated circuit to provide~~
~~driving.~~

9. (Currently Amended) The optical interconnection circuit between chips
according to claim 8,

~~further including the integrated circuit to provide driving including at least a plurality of the integrated circuits to provide driving, which are mounted onto the substrate; and~~

~~_____ at least one of the plurality of a single of the optical wave-guides wave-guide being provided for each of the plurality of the integrated circuits to provide driving.~~

10. (Currently Amended) The optical interconnection circuit between chips according to ~~claim 8 claim 9,~~

~~the integrated circuit to time control being electrically connected to a number of the plurality of first elements micro-tile element that is larger than the number of the integrated circuits which corresponds to the integrated circuit to provide driving mounted onto the substrate.~~

11. (Currently Amended) The optical interconnection circuit between chips according to claim 8,

~~the integrated circuit to provide driving being electrically connected to at least one of the plurality of second-micro-tile-element elements.~~

12. (Original) The optical interconnection circuit between chips according to claim 1,

~~the optical wave-guide being treated to prevent extraneous light from entering the optical wave-guide.~~

13. (Currently Amended) The optical interconnection circuit between chips according to ~~claim 1 claim 8,~~

~~the first micro-tile element including at least a plurality of first micro-tile elements provided on the substrate; and~~

the plurality of a plurality of the first micro-tile elements emitting a light
having at least two kinds of wavelengths that are different from each other to the plurality of
~~optical-wave-guide~~ wave-guides.

14. (Currently Amended) The optical interconnection circuit between chips
according to claim 1,

the optical wave-guide including a light scattering mechanism scattering a
light emitted by the first element, ~~which is installed in the vicinity of at least one of the first~~
~~micro-tile element and the second micro-tile element.~~

15. (Original) The optical interconnection circuit between chips according to
claim 14,

the light scattering mechanism being composed of a resin into which a light
scattering particle is mixed.

16. (Original) The optical interconnection circuit between chips according to
claim 14,

the light scattering mechanism being composed of a resin of which a surface is
processed to include an irregularity thereon.

17. (Original) The optical interconnection circuit between chips according to
claim 14,

the light scattering mechanism being composed of the optical wave-guide
member of which at least one of the line width and the height differ from the other.

18. (Original) The optical interconnection circuit between chips according to
claim 14,

the light scattering mechanism being composed of at least one of a resin and a
glass in which a light scattering particle is dispersed, and being dome-shaped.

19. (Original) An electrooptical device, comprising:
the optical interconnection circuit between chips according to claim 1.
20. (Currently Amended) An electronic ~~Electronic~~ equipment, comprising:
the optical interconnection circuit between chips according to claim 1.